Thermal TP0200LD 低密度导热灌封胶

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Thermal TP0200LD 导热灌封胶是一种双组份加成型有机硅体系，具有导热率高，流动性好，低密度，优越的电气绝缘性能和阻燃性能。该产品适用于高功率电源及模块，电流/功率转换单元，高功率车载充电器及充电桩等高功率器件，可满足电气/电子封装领域对高导热性的要求，同时又能保持有机硅的理想特性。

Thermal TP0200LD thermally conductive potting compound is a two-component additional type silicone base with high thermal conductivity, good flowability, low density, superior electrical insulation and flame retardancy. It's suitable for high-power devices such as high-power supplies and modules, current/power conversion units, high power on-board chargers and charging piles. The product can meet the requirements for high thermal conductivity in the electrical/electronic packaging field and maintaining silicone polymer characteristics.

Features 特性

- Low Viscosity 低粘度
- Low Density 低密度
- Easy Handling 易操作
- High Reliability 高可靠性

Applications 产品应用

- Motor Potting 电机灌封
- Power Module 电源模块
- Charging Pile 充电桩
- ADAS 智能驾驶系统

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体		—
Color 颜色	A – Gray 灰色 B – White 白色 Mix – Gray 灰色		Visual 目视
Thermal Conductivity 导热系数	>= 1.8	W/m·K	ASTM D5470
Viscosity 粘度 (A/B)	5000 ± 1000	mPa.s	ASTM D2196
Density 密度	2.0 ± 0.1	g/cm^3	ASTM D792
Hardness 硬度 (Shore A)	30 ± 10	—	ASTM D2240
Tacky-Free Time 表干时间	>= 30min @ RT	—	—
Cure Time 固化时间	24H @ RT 15min @ 150°C	—	—
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	>= 8.0	KV/mm	ASTM D149
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	6	month	25±5°C, ≤50% RH